

HANWA

Standard compliant needle-wafer contact point

Wafer ESD Tester

HED-W5000 M

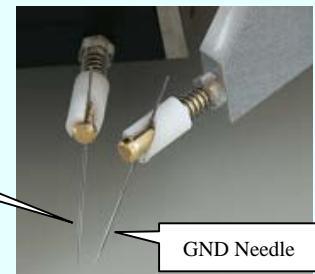


ESD testing of packages and wafers is now possible!

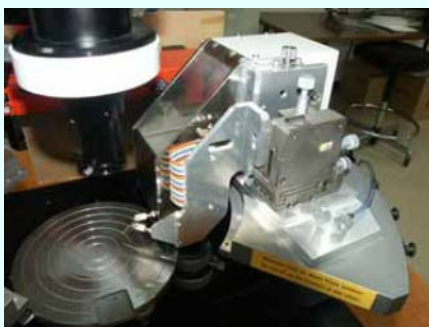
Features

1. The real device's ESD waveform can be displayed **NEW**
2. Performs automatic destructive evaluation of V/I measurement after zap for excellent cost performance.
3. Performs HBM/MM zap (Complies with JEDEC/ESDA/JEITA).
4. Connects with two needles to any device such as wafers.
5. Zap unit can be installed on the customer's manual PROBER.
6. Clear correlation of the test results of a package device.

Zap Needle



GND Needle



Setting view

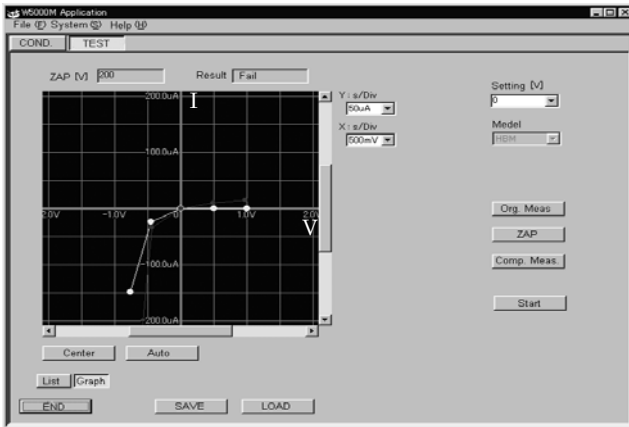


Zap unit

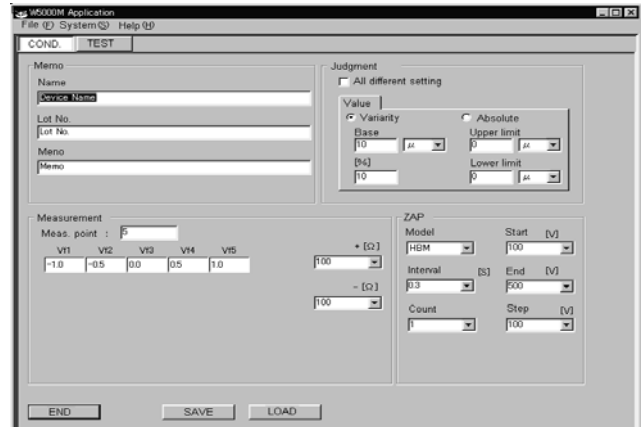


Position adjustment button

Operation screen



Curve tracing



Setting screen

Specification

HED-W5000 series

Model	HED-W5000M	
Waveform	HBM JEDEC EIA/JESD22-A114-B, ESDA STM5.1-1998, MIL-STD 883E	
	MM JEDEC EIA/JESD22-A115-A, ESDA STM5.2-1999,	
Charging voltage	0 ~ +/-4kV (8kV option)	
Charging resolution	10V	
Charging accuracy	1 % +/-5V	
ZAP count	1 ~ 9	
Interval time	0.3 ~ 9.9 S	
Test pins	Manual positioning	
X-Y movable range	8 mm * 8mm manual (only GND Unit)	
Z movable range	8mm manual	
Moving resolution	-	
Physical	740(W) / 550(D) / 610(H) (PC no contained)	
Weight	10 Kg	
Curve Tracing voltage	0 ~ +/- 10V	
Curve Tracing Resolution	0.1V	
Curve Tracing current	Max 100mA	
Detection resistance	100,1k,10k,100k ohm	
Measurement range	100nA, 1uA, 10uA, 100uA, 1mA, 10mA, 100mA	
Curve Tracing Accuracy	1% of range	
Measurement point	Max 20	
Judgment	Relatively and Absolute value	
Control	RS-232C and manual	
Operation	Windows	

HANWA HANWA ELECTRONIC IND.CO.LTD
 Headquarters: 689-3,Ogaito, Wakayama Pref.649-6272, Japan
 TEL:+81-73-477-4435 FAX:+81-73-477-3445
 Kumamoto Plant: TEL:+81-968-34-3339 FAX:+81-968-34-3369
 Tokyo Office: TEL:+81-3-5767-5677 FAX:+81-3-5767-5688
<http://www.hanwa-ei.co.jp/> info@hanwa-ei.co.jp

● Agent